SEMICONDUCTOR

DATA SHEET

YSESD3ZxxBT1G Series

BIDIRECTIONAL TVS DIODES

APPLICATIONS

- Cell Phone Handsets and Accessories
- Microprocessor based equipment
- Personal Digital Assistants (PDA's)
- Notebooks, Desktops, and Servers
- Portable Instrumentation
- Peripherals
- Pagers

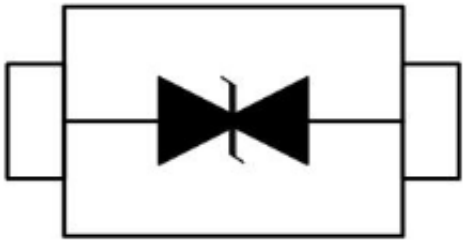
SOD-323



IEC COMPATIBILITY

- IEC61000-4-2 (ESD) ±15kV (air), ±8kV (contact)
- IEC61000-4-4 (EFT) 40A (5/50 η s)
- IEC61000-4-5 (Lightning) 24A (8/20μs)

PIN CONFIGURATION



FEATURES

- 350 Watts Peak Pulse Power per Line (tp=8/20μs)
- Protects one I/O or power line
- Low clamping voltage
- Working voltages: 3.3V ~ 36V
- Low leakage current

MECHANICAL CHARACTERISTICS

- SOD-323 Package
- Molding Compound Flammability Rating : UL 94V-O
- Weight 5 Millgrams (Approximate)
- Quantity Per Reel : 3,000pcs
- Reel Size : 7 inch
- Lead Finish : Lead Free

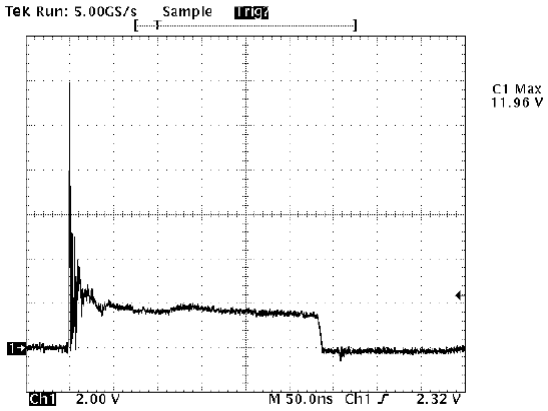
DEVICE CHARACTERISTICS

YSESD3ZxxBT1G Series

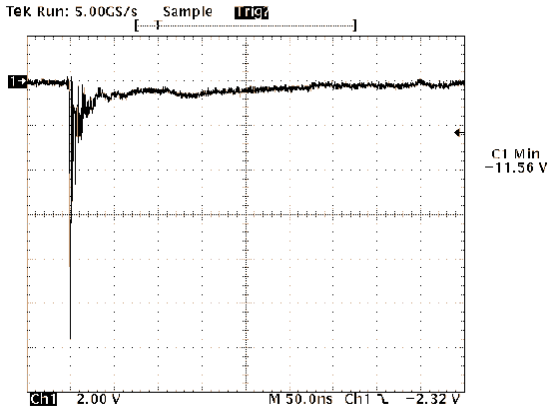
MAXIMUM RATINGS (@ 25℃ Unless Otherwise Specified)			
PARAMETER	SYMBOL	VALUE	UNITS
Peak Pulse Power (tp=8/20μs waveform)	P_{PP}	350	Watts
Lead Soldering Temperature	T_L	260 (10 sec.)	℃
Operating Temperature Range	T_J	-55 ~ 150	℃
Storage Temperature Range	T_{STG}	-55 ~ 150	℃

ELECTRICAL CHARACTERISTICS PER LINE (@ 25℃ Unless Otherwise Specified)									
PART NUMBER	DEVICE MARKING	V_{RWM} (V) (max.)	V_B (V) (min.)	I_T (mA)	V_C @1A (max.)	V_C (max.)	V_C (@A)	I_R (μA) (max.)	C_T (pF) (max.)
YSESD3Z3.3BT1G	2A	3.3	4	1	7	10.5	20	40	450
YSESD3Z05BT1G	2B	5	6	1	9.8	18	17	10	200
YSESD3Z08BT1G	2C	8	8.5	1	13.4	24	12	1	100
YSESD3Z12BT1G	2D	12	13.3	1	19	32	11	1	75
YSESD3Z15BT1G	2J	15	16.7	1	24	38	10	1	68
YSESD3Z18BT1G	2K	18	20	1	29	45	9	1	57
YSESD3Z24BT1G	2H	24	26.7	1	43	52	7	1	50
YSESD3Z36BT1G	2N	36	40	1	60	75	5	1	40

ESD Clamping
(8kV Contact per IEC 61000-4-2)

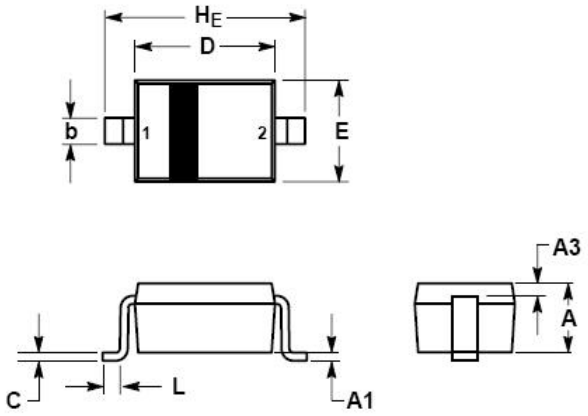


ESD Clamping
(-8kV Contact per IEC 61000-4-2)



PACKAGE OUTLINE & DIMENSIONS

YSESD3ZxxBT1G Series



	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
A	0.80	0.90	1.00	0.031	0.035	0.040
A1	0.00	0.05	0.10	0.000	0.002	0.004
A3	0.15 REF			0.006 REF		
b	0.25	0.32	0.4	0.010	0.012	0.016
C	0.089	0.12	0.177	0.003	0.005	0.007
D	1.60	1.70	1.80	0.062	0.066	0.070
E	1.15	1.25	1.35	0.045	0.049	0.053
L	0.08			0.003		
H_E	2.30	2.50	2.70	0.090	0.098	0.105

* SOLDERING FOOTPRINT

